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Assistant Commissioner for Patents
Washington, D.C. 20231

On July 18, 2002

TOWNSEND and TOWNSEND and CREW LLP

By: Lisa Kaeder

PATENT
Attorney Docket No.: 018865-007400US
Client Ref. No.: 17732.39260

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8/8/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Ruben Madrid

Application No.: 09/855,820

Filed: May 14, 2001

For: CARRIER WITH METAL BUMPS
FOR SEMICONDUCTOR DIE
PACKAGES

Examiner: E. Wojciechowicz

Art Unit: 2811

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed March 18, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 4, 11, and 25.

1. (Amended) A carrier for a semiconductor die package, the carrier comprising:

- (a) a metal layer; and
- (b) a plurality of bumps formed in the metal layer,

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